

Board Level Cooling – Extruded YB



BOARD LEVEL COOLING - Extruded YB

Extruded YB is a dual radial board level heat sink designed to cool Multiwatt and SIP devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
YB324G	Multiwatt, SIP



HEAT SINK DETAILS

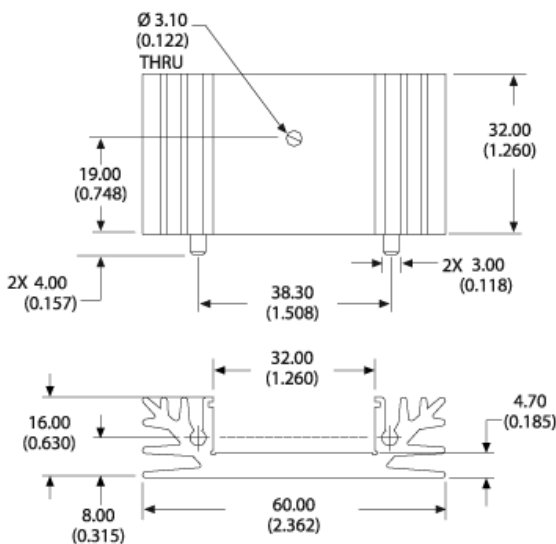
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Requires Mounting Kit
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	60.00
Heat Sink Length (mm)	16.00
Heat Sink Height (mm)	32.00
Heat Sink Mounting Direction	Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number	"X" Dim	"Y" Dim	"Z" Dim
YB324G	19.15 (0.754)	3.30 (0.130)	3.48 (0.137)



Mounting details:

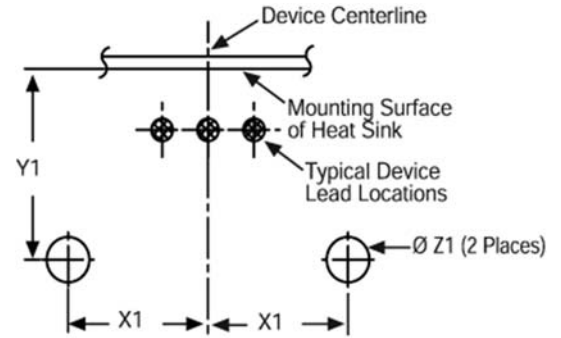


FIGURE 1

